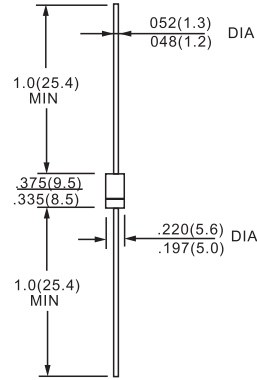




**FEATURES**

- High efficiency
- Low power losses
- Very low switching losses
- Low reverse current
- High surge capability

DO-27



Dimensions in inches and (millimeters)

**MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS**

**ABSOLUTE MAXIMUM RATINGS** (limiting values)

Symbol	Parameter	Value	Unit
$I_{FRM}$	Repetive Peak Forward Current	$t_p \leq 20\mu s$	50 A
$I_{F(AV)}$	Average Forward Current *	$T_a = 55^\circ C$ $\delta = 0.5$	3 A
$I_{FSM}$	Surge non Repetitive Forward Current	$t_p = 10ms$ Sinusoidal	100 A
$P_{tot}$	Power Dissipation *	$T_a = 55^\circ C$	3.75 W
$T_{stg}$ $T_j$	Storage and Junction Temperature Range	- 40 to + 150 - 40 to + 150	$^\circ C$
$T_L$	Maximum Lead Temperature for Soldering during 10s at 4mm from Case	230	$^\circ C$

Symbol	Parameter	BYT 13-			Unit
		600	800	1000	
$V_{RRM}$	Repetitive Peak Reverse Voltage	600	800	1000	V

**THERMAL RESISTANCE**

Symbol	Parameter	Value	Unit
$R_{th(j-a)}$	Junction-ambient*	25	$^\circ C/W$

**STATIC CHARACTERISTICS**

Synbol	Test Conditions	Min.	Typ.	Max.	Unit
$I_R$	$T_j = 25^\circ C$ $V_R = V_{RRM}$			20	$\mu A$
$V_F$	$T_j = 25^\circ C$ $I_F = 3A$			1.3	V



**RATINGS AND CHARACTERISTIC CURVES BYT13-600 THRU BYT13-1000**

Figure 1. Maximum average power dissipation versus average forward current.

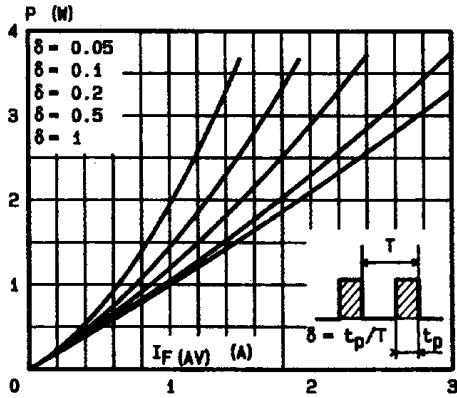


Figure 2. Average forward current versus ambient temperature.

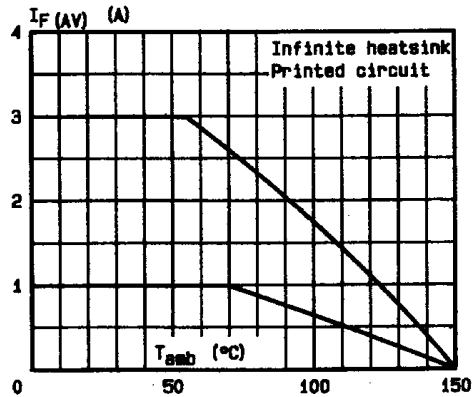


Figure 3. Thermal resistance versus lead length.

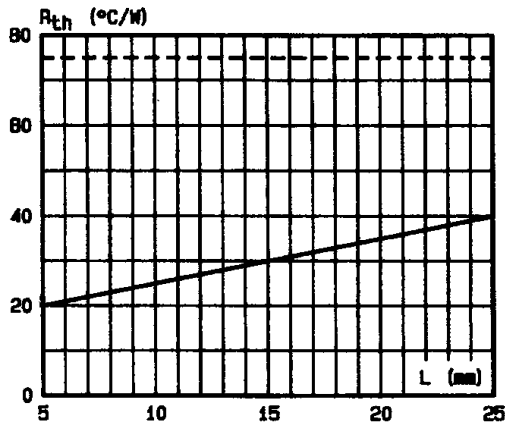


Figure 5. Peak forward current versus peak forward voltage drop (maximum values).

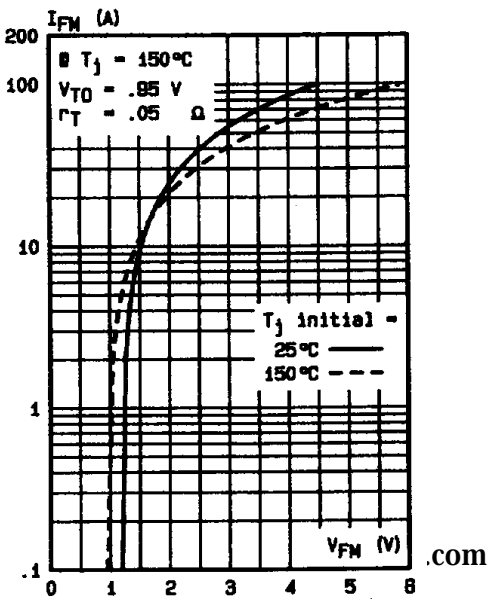


Figure 4. Transient thermal impedance junction-ambient for mounting n² versus pulse duration (L = 10 mm).

